


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	Adapter Board for Stacking Ball-Grid-Array (BGA) chips	
<p>Application Type : regular, utility</p> <p>Attorney Docket Number : PS-108</p> <p>Request Not To Publish</p> <p>I/We hereby request that the attached application not be published under 37 U.S.C. 122(b).</p> <p>I/We hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.</p>		
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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.